

PATENT

Docket No.: JCLA4280-D2

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

#2

Pre Amended
5-21-07
R. Stokes

Applicant: MING-DOU KER et al.)
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Filed: Herewith)
)
For: LOW-CAPACITANCE BONDING PAD FOR)
SEMICONDUCTOR DEVICE)
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)

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

Prior to the examination on merits, please amend the above-identified application as follows:

IN THE SPECIFICATION:

On page 1, lines 5-7, please replace "This application claims the priority benefit of Taiwan application serial no. 88104304, filed March 19, 1999, the full disclosure of which is incorporated herein by reference." with "This application is a divisional application of, and claims the priority benefit of, U.S. application serial No. 09/329,648 filed on June 09, 1999."

IN THE CLAIMS:

Please cancel claims 1-25.

Please add the following new claims:

26. (Newly Added) A low-capacitance bonding pad for a semiconductor device, comprising:
a substrate;